

Electrical test :100% passed

Final Board thickness:1.8+/-0.15mm

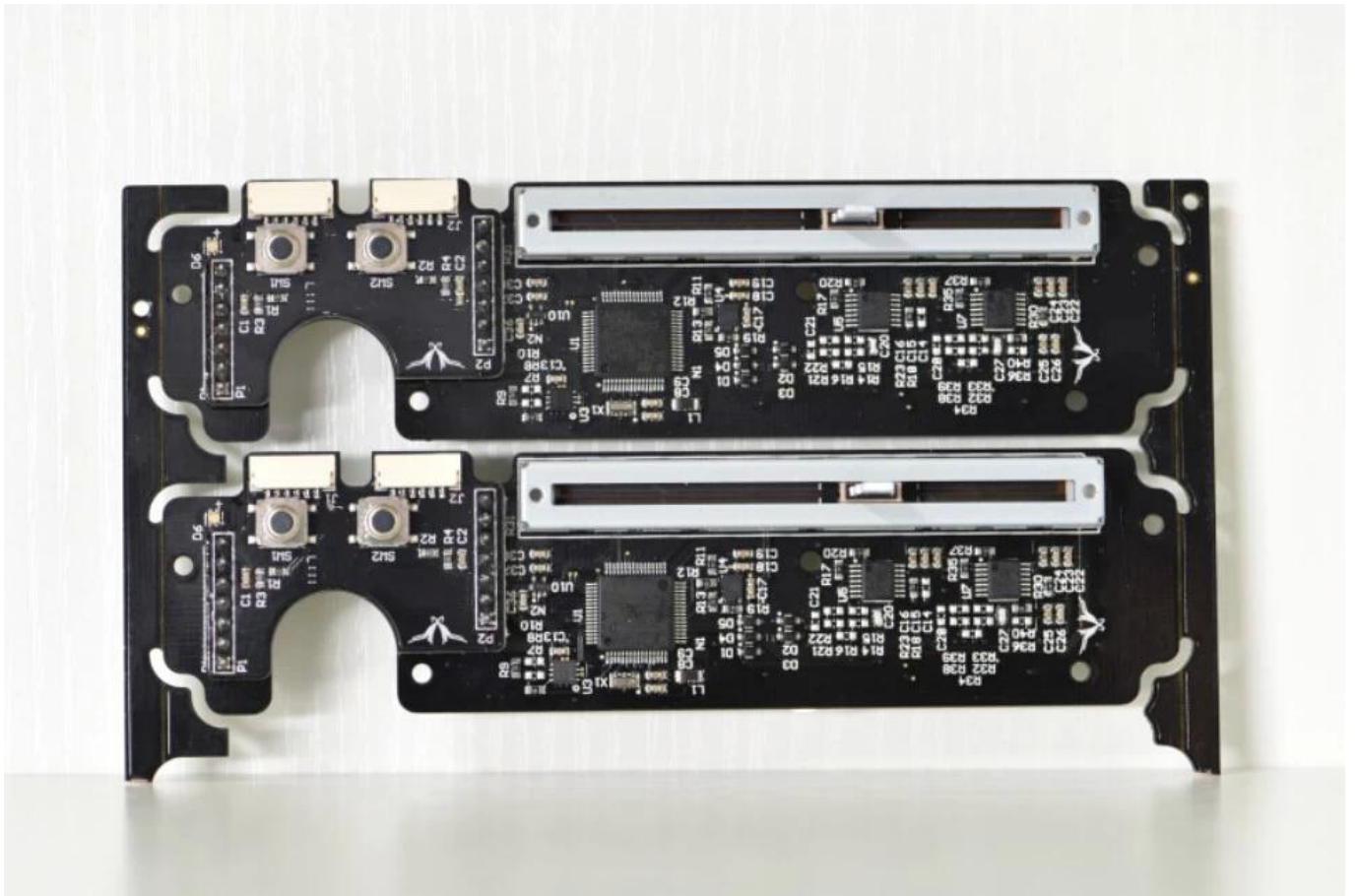
FINISH: THIS BOARD SHALL BE IMMERSION GOLD PLATED ACCORDING TO IPC-6012. THICKNESS SHALL BE .050uM OVER 3-6uM NICKEL.

COPPER PLATE HOLES MINIMUM .025 AVG, .020 MIN.. HOLES MAY NOT BE PLUGGED,

Packaging & Delivery

Packaging Details:	Vacuum packaged
Delivery Detail:	7-10days





factory: [china Mobile phone pcb board manufacture, Holgen free pcb manufacturer china](#)